

CLAIMS

1. A circuit assembly comprising a circuit board (2), at least one circuit component (7) connected to the circuit board (2) by wire bonding, and a base plate (1) on which the circuit board (2) is fixed; characterized in that the gap (12) between the base plate (1) and the circuit board (2) fixed to it is at least locally filled with a filling body (14) of a material hardened in the gap (12).
2. A circuit assembly according to claim 1, characterized in that the filling body (14) is located at a hole (11) in the circuit board (2).
3. The circuit assembly of claim 2, characterized in that the filling body (14) engages the hole (11).
4. The circuit assembly of claim 2 or 3, characterized in that the filling body (14) extends into the gap (12) beyond the edges of the hole (11).
5. The circuit assembly according to any preceding claim, characterized in that the hole (11) is free from metallization.
6. The circuit assembly according to any preceding claim, characterized in that the hardened material is an adhesive.
7. The circuit assembly of claim 6, characterized in that the adhesive is electrically conductive.

8. The circuit assembly according to any preceding claim, characterized in that the at least one filling body (14) is located adjacent to at least one bond pad (8).

9. The circuit assembly of claim 8, characterized in that at least two filling bodies (14) are located at different sides of a bond pad (8).

10. A method for manufacturing a circuit assembly, comprising the steps of:
a) fixing a circuit board (2) and at least one circuit component (7) on a base plate (1),
b) applying at least one bonding wire (9) between the circuit component (7) and a bond pad (8) of the circuit board (2), and characterized in that between steps a) and b), a hardenable material is introduced into a gap (12) between the circuit board (2) and the base plate (1) and is hardened in the gap (12).

11. The method of claim 10, characterized in that the hardenable material is introduced into the gap (12) using capillary force.

12. The method of claim 10 or 11, characterized in that the hardenable material is introduced into the gap (12) through a hole (11) in the circuit board (2).

13. The method of any of claims 10, 11 or 12, characterized in that the hardenable material is an adhesive which is also used for cementing components (4, 5, 7) to the circuit board (2) and/or the base plate (1), and that the adhesive is introduced into the

gap (12) and is applied to the circuit board (2) and/or the base plate (1) for cementing the components (4, 5, 7) in a same step.

14. The method of claims 10 to 13, characterized in that the bonding wire (9) is mounted by ultrasonic welding.